POLITECNICO DI TORINO
ESAMI DI STATO PER L'ABILITAZIONE ALL'ESERCIZIO
DELLA PROFESSIONE DI INGEGNERE DELL'INFORMAZIONE IUNIOR

II Sessione 2019 - Sezione B
Settore dell'Informazione

Prova PRATICA del 20 dicembre 2019

Il Candidato svolga uno a scelta fra i seguenti temi proposti.
Gli elaborati prodotti dovranno essere stilati in forma chiara, ordinata, sintetica e leggibile.
La completezza, l'attinenza e la chiarezza espositiva costituiranno elementi di valutazione.

Tema n. 1

Progettare un amplificatore di tensione non invertente avente le seguenti specifiche.

Specifiche e dati

- Amplificazione di tensione A_v=5
- Tensione di ingresso -2V $\leq V_{in} \leq$ 2V
- Carico da pilotare R_L=100 Ω
- Si utilizzi un amplificatore operazionale LM741alimentato a ±15V
- Si progetti il circuito affinché funzioni correttamente per variazioni della temperatura ambiente 0°C ≤ T ≤ 70°C
- Il circuito richiesto deve includere i circuiti di protezione al corto circuito verso massa

Sulla base delle specifiche, il candidato:

- proponga uno schema complessivo del sistema che possa realizzare le funzionalità richieste, descrivendo nel dettaglio il funzionamento di ciascun blocco utilizzato;
- dimensioni correttamente tutti i componenti necessari in modo da soddisfare le specifiche di progetto.

Allegati:

- Datasheet dell'amplificatore operazionale LM741

Allegato Tema 1

LM741 Operational Amplifier

1 Features

- Overload Protection on the Input and Output
- No Latch-Up When the Common-Mode Range is Exceeded

2 Applications

- Comparators
- Multivibrators
- DC Amplifiers
- Summing Amplifiers
- Integrator or Differentiators
- Active Filters

3 Description

The LM741 series are general-purpose operational amplifiers which feature improved performance over industry standards like the LM709. They are direct, plug-in replacements for the 709C, LM201, MC1439, and 748 in most applications.

The amplifiers offer many features which make their application nearly foolproof: overload protection on the input and output, no latch-up when the common-mode range is exceeded, as well as freedom from oscillations.

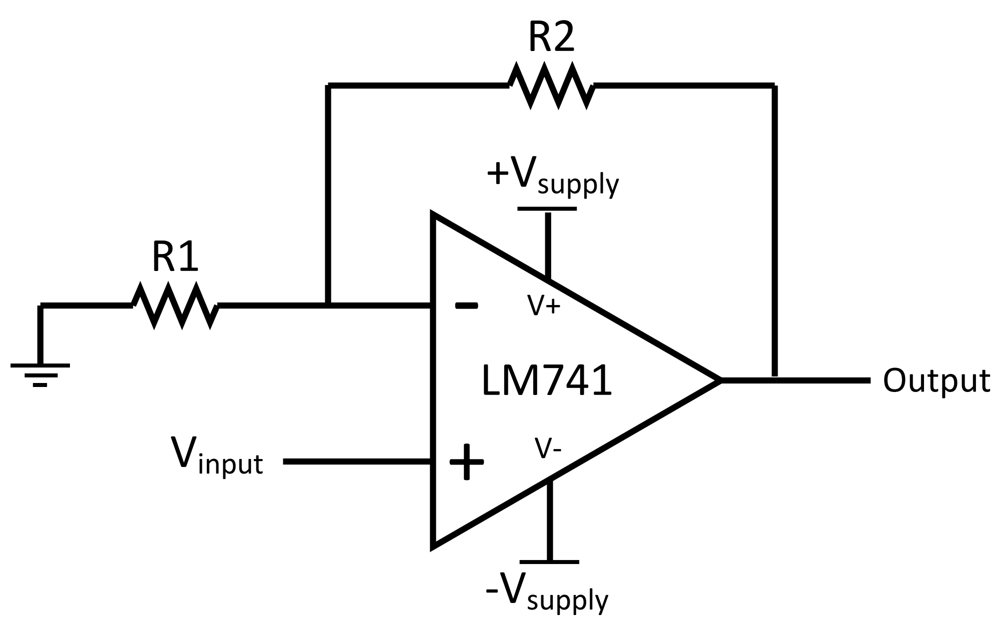
The LM741C is identical to the LM741 and LM741A except that the LM741C has their performance ensured over a 0°C to +70°C temperature range, instead of −55°C to +125°C.

Device Information(1)

PART NUMBER	PACKAGE	BODY SIZE (NOM)
LM741	TO-99 (8)	9.08 mm × 9.08 mm
	CDIP (8)	10.16 mm × 6.502 mm
	PDIP (8)	9.81 mm × 6.35 mm

(1) For all available packages, see the orderable addendum at the end of the data sheet.

Typical Application



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4 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from Revision C (October 2004) to Revision D — **Page**

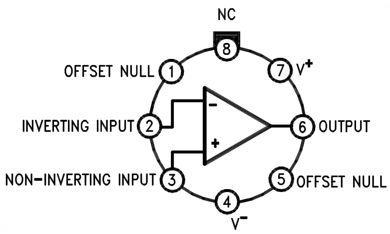
- Added *Applications* section, *Pin Configuration and Functions* section, *ESD Ratings* table, *Feature Description* section, *Device Functional Modes*, *Application and Implementation* section, *Power Supply Recommendations* section, *Layout* section, *Device and Documentation Support* section, and *Mechanical, Packaging, and Orderable Information* section 1
- Removed NAD 10-Pin CLGA pinout 3
- Removed obselete M (S0-8) package from the data sheet 4
- Added recommended operating supply voltage spec 4
- Added recommended operating temperature spec 4

Changes from Revision C (March 2013) to Revision D — **Page**

- Added *Applications* section, *Pin Configuration and Functions* section, *ESD Ratings* table, *Feature Description* section, *Device Functional Modes*, *Application and Implementation* section, *Power Supply Recommendations* section, *Layout* section, *Device and Documentation Support* section, and *Mechanical, Packaging, and Orderable Information* section 1
- Removed NAD 10-Pin CLGA pinout 3
- Removed obselete M (S0-8) package from the data sheet 4
- Added recommended operating supply voltage spec 4
- Added recommended operating temperature spec 4

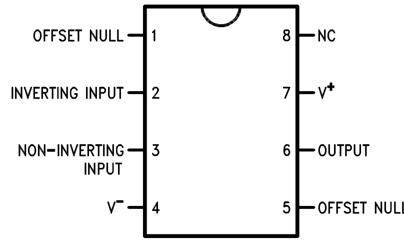
5 Pin Configuration and Functions

LMC Package
8-Pin TO-99
Top View



LM741H is available per JM38510/10101

NAB Package
8-Pin CDIP or PDIP
Top View



Pin Functions

PIN		I/O	DESCRIPTION
NAME	NO.		
INVERTING INPUT	2	I	Inverting signal input
NC	8	N/A	No Connect, should be left floating
NONINVERTING INPUT	3	I	Noninverting signal input
OFFSET NULL	1, 5	I	Offset null pin used to eliminate the offset voltage and balance the input voltages.
OFFSET NULL			
OUTPUT	6	O	Amplified signal output
V+	7	I	Positive supply voltage
V–	4	I	Negative supply voltage

6 Specifications

6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)(1)(2)(3)

		MIN	MAX	UNIT
Supply voltage	LM741, LM741A		±22	V
	LM741C		±18	
Power dissipation (4)			500	mW
Differential input voltage			±30	V
Input voltage (5)			±15	V
Output short circuit duration		Continuous		
Operating temperature	LM741, LM741A	–50	125	°C
	LM741C	0	70	
Junction temperature	LM741, LM741A		150	°C
	LM741C		100	
Soldering information	PDIP package (10 seconds)		260	°C
	CDIP or TO-99 package (10 seconds)		300	°C
Storage temperature, T_{stg}		–65	150	°C

(1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
(2) For military specifications see RETS741X for LM741 and RETS741AX for LM741A.
(3) If Military/Aerospace specified devices are required, please contact the TI Sales Office/Distributors for availability and specifications.
(4) For operation at elevated temperatures, these devices must be derated based on thermal resistance, and T_j max. (listed under "Absolute Maximum Ratings"). $T_j = T_A + (\theta_{jA} P_D)$.
(5) For supply voltages less than ±15 V, the absolute maximum input voltage is equal to the supply voltage.

6.2 ESD Ratings

			VALUE	UNIT
$V_{(ESD)}$	Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001 (1)	±400	V

(1) Level listed above is the passing level per ANSI, ESDA, and JEDEC JS-001. JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.

6.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

		MIN	NOM	MAX	UNIT
Supply voltage (VDD-GND)	LM741, LM741A	±10	±15	±22	V
	LM741C	±10	±15	±18	
Temperature	LM741, LM741A	–55		125	°C
	LM741C	0		70	

6.4 Thermal Information

THERMAL METRIC (1)		LM741			UNIT
		LMC (TO-99)	NAB (CDIP)	P (PDIP)	
		8 PINS	8 PINS	8 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	170	100	100	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	25	—	—	°C/W

(1) For more information about traditional and new thermal metrics, see the *Semiconductor and IC Package Thermal Metrics* application report, SPRA953.

6.5 Electrical Characteristics, LM741[(1)]

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
Input offset voltage		$R_S \le 10$ kΩ	$T_A = 25°C$		1	5	mV
			$T_{AMIN} \le T_A \le T_{AMAX}$			6	mV
Input offset voltage adjustment range		$T_A = 25°C$, $V_S = \pm 20$ V			±15		mV
Input offset current		$T_A = 25°C$			20	200	nA
		$T_{AMIN} \le T_A \le T_{AMAX}$			85	500	
Input bias current		$T_A = 25°C$			80	500	nA
		$T_{AMIN} \le T_A \le T_{AMAX}$				1.5	µA
Input resistance		$T_A = 25°C$, $V_S = \pm 20$ V		0.3	2		MΩ
Input voltage range		$T_{AMIN} \le T_A \le T_{AMAX}$		±12	±13		V
Large signal voltage gain		$V_S = \pm 15$ V, $V_O = \pm 10$ V, $R_L \ge 2$ kΩ	$T_A = 25°C$	50	200		V/mV
			$T_{AMIN} \le T_A \le T_{AMAX}$	25			
Output voltage swing		$V_S = \pm 15$ V	$R_L \ge 10$ kΩ	±12	±14		V
			$R_L \ge 2$ kΩ	±10	±13		
Output short circuit current		$T_A = 25°C$			25		mA
Common-mode rejection ratio		$R_S \le 10$ Ω, $V_{CM} = \pm 12$ V, $T_{AMIN} \le T_A \le T_{AMAX}$		80	95		dB
Supply voltage rejection ratio		$V_S = \pm 20$ V to $V_S = \pm 5$ V, $R_S \le 10$ Ω, $T_{AMIN} \le T_A \le T_{AMAX}$		86	96		dB
Transient response	Rise time	$T_A = 25°C$, unity gain			0.3		µs
	Overshoot				5%		
Slew rate		$T_A = 25°C$, unity gain			0.5		V/µs
Supply current		$T_A = 25°C$			1.7	2.8	mA
Power consumption		$V_S = \pm 15$ V	$T_A = 25°C$		50	85	mW
			$T_A = T_{AMIN}$		60	100	
			$T_A = T_{AMAX}$		45	75	

(1) Unless otherwise specified, these specifications apply for $V_S = \pm 15$ V, $-55°C \le T_A \le +125°C$ (LM741/LM741A). For the LM741C/LM741E, these specifications are limited to $0°C \le T_A \le +70°C$.

6.6 Electrical Characteristics, LM741A[(1)]

PARAMETER	TEST CONDITIONS		MIN	TYP	MAX	UNIT
Input offset voltage	$R_S \le 50$ Ω	$T_A = 25°C$		0.8	3	mV
		$T_{AMIN} \le T_A \le T_{AMAX}$			4	mV
Average input offset voltage drift					15	µV/°C
Input offset voltage adjustment range	$T_A = 25°C$, $V_S = \pm 20$ V		±10			mV
Input offset current	$T_A = 25°C$			3	30	nA
	$T_{AMIN} \le T_A \le T_{AMAX}$				70	
Average input offset current drift					0.5	nA/°C
Input bias current	$T_A = 25°C$			30	80	nA
	$T_{AMIN} \le T_A \le T_{AMAX}$				0.21	µA
Input resistance	$T_A = 25°C$, $V_S = \pm 20$ V		1	6		MΩ
	$T_{AMIN} \le T_A \le T_{AMAX}$, $V_S = \pm 20$ V		0.5			
Large signal voltage gain	$V_S = \pm 20$ V, $V_O = \pm 15$ V, $R_L \ge 2$ kΩ	$T_A = 25°C$	50			V/mV
		$T_{AMIN} \le T_A \le T_{AMAX}$	32			
	$V_S = \pm 5$ V, $V_O = \pm 2$ V, $R_L \ge 2$ kΩ, $T_{AMIN} \le T_A \le T_{AMAX}$		10			

(1) Unless otherwise specified, these specifications apply for $V_S = \pm 15$ V, $-55°C \le T_A \le +125°C$ (LM741/LM741A). For the LM741C/LM741E, these specifications are limited to $0°C \le T_A \le +70°C$.

Electrical Characteristics, LM741A(1) (continued)

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
Output voltage swing		V_S = ±20 V	R_L ≥ 10 kΩ	±16			V
			R_L ≥ 2 kΩ	±15			
Output short circuit current		T_A = 25°C		10	25	35	mA
		T_{AMIN} ≤ T_A ≤ T_{AMAX}		10		40	
Common-mode rejection ratio		R_S ≤ 50 Ω, V_{CM} = ±12 V, T_{AMIN} ≤ T_A ≤ T_{AMAX}		80	95		dB
Supply voltage rejection ratio		V_S = ±20 V to V_S = ±5 V, R_S ≤ 50 Ω, T_{AMIN} ≤ T_A ≤ T_{AMAX}		86	96		dB
Transient response	Rise time	T_A = 25°C, unity gain			0.25	0.8	µs
	Overshoot				6%	20%	
Bandwidth (2)		T_A = 25°C		0.437	1.5		MHz
Slew rate		T_A = 25°C, unity gain		0.3	0.7		V/µs
Power consumption		V_S = ±20 V	T_A = 25°C		80	150	mW
			T_A = T_{AMIN}			165	
			T_A = T_{AMAX}			135	

(2) Calculated value from: BW (MHz) = 0.35/Rise Time (µs).

6.7 Electrical Characteristics, LM741C(1)

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
Input offset voltage		R_S ≤ 10 kΩ	T_A = 25°C		2	6	mV
			T_{AMIN} ≤ T_A ≤ T_{AMAX}			7.5	mV
Input offset voltage adjustment range		T_A = 25°C, V_S = ±20 V			±15		mV
Input offset current		T_A = 25°C			20	200	nA
		T_{AMIN} ≤ T_A ≤ T_{AMAX}				300	
Input bias current		T_A = 25°C			80	500	nA
		T_{AMIN} ≤ T_A ≤ T_{AMAX}				0.8	µA
Input resistance		T_A = 25°C, V_S = ±20 V		0.3	2		MΩ
Input voltage range		T_A = 25°C		±12	±13		V
Large signal voltage gain		V_S = ±15 V, V_O = ±10 V, R_L ≥ 2 kΩ	T_A = 25°C	20	200		V/mV
			T_{AMIN} ≤ T_A ≤ T_{AMAX}	15			
Output voltage swing		V_S = ±15 V	R_L ≥ 10 kΩ	±12	±14		V
			R_L ≥ 2 kΩ	±10	±13		
Output short circuit current		T_A = 25°C			25		mA
Common-mode rejection ratio		R_S ≤ 10 kΩ, V_{CM} = ±12 V, T_{AMIN} ≤ T_A ≤ T_{AMAX}		70	90		dB
Supply voltage rejection ratio		V_S = ±20 V to V_S = ±5 V, R_S ≤ 10 Ω, T_{AMIN} ≤ T_A ≤ T_{AMAX}		77	96		dB
Transient response	Rise time	T_A = 25°C, Unity Gain			0.3		µs
	Overshoot				5%		
Slew rate		T_A = 25°C, Unity Gain			0.5		V/µs
Supply current		T_A = 25°C			1.7	2.8	mA
Power consumption		V_S = ±15 V, T_A = 25°C			50	85	mW

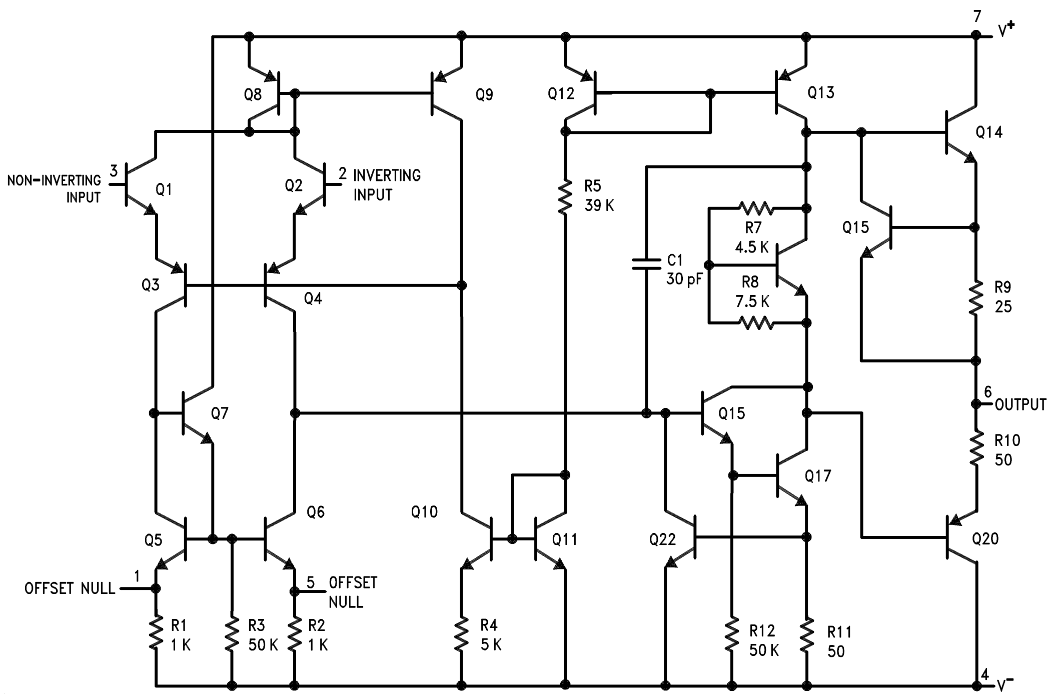
(1) Unless otherwise specified, these specifications apply for V_S = ±15 V, −55°C ≤ T_A ≤ +125°C (LM741/LM741A). For the LM741C/LM741E, these specifications are limited to 0°C ≤ T_A ≤ +70°C.

7 Detailed Description

7.1 Overview

The LM74 devices are general-purpose operational amplifiers which feature improved performance over industry standards like the LM709. It is intended for a wide range of analog applications. The high gain and wide range of operating voltage provide superior performance in integrator, summing amplifier, and general feedback applications. The LM741 can operate with a single or dual power supply voltage. The LM741 devices are direct, plug-in replacements for the 709C, LM201, MC1439, and 748 in most applications.

7.2 Functional Block Diagram



7.3 Feature Description

7.3.1 Overload Protection

The LM741 features overload protection circuitry on the input and output. This prevents possible circuit damage to the device.

7.3.2 Latch-up Prevention

The LM741 is designed so that there is no latch-up occurrence when the common-mode range is exceeded. This allows the device to function properly without having to power cycle the device.

7.3.3 Pin-to-Pin Capability

The LM741 is pin-to-pin direct replacements for the LM709C, LM201, MC1439, and LM748 in most applications. Direct replacement capabilities allows flexibility in design for replacing obsolete parts.

7.4 Device Functional Modes

7.4.1 Open-Loop Amplifier

The LM741 can be operated in an open-loop configuration. The magnitude of the open-loop gain is typically large thus for a small difference between the noninverting and inverting input terminals, the amplifier output will be driven near the supply voltage. Without negative feedback, the LM741 can act as a comparator. If the inverting input is held at 0 V, and the input voltage applied to the noninverting input is positive, the output will be positive. If the input voltage applied to the noninverting input is negative, the output will be negative.

7.4.2 Closed-Loop Amplifier

In a closed-loop configuration, negative feedback is used by applying a portion of the output voltage to the inverting input. Unlike the open-loop configuration, closed loop feedback reduces the gain of the circuit. The overall gain and response of the circuit is determined by the feedback network rather than the operational amplifier characteristics. The response of the operational amplifier circuit is characterized by the transfer function.

8 Application and Implementation

NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

8.1 Application Information

The LM741 is a general-purpose amplifier than can be used in a variety of applications and configurations. One common configuration is in a noninverting amplifier configuration. In this configuration, the output signal is in phase with the input (not inverted as in the inverting amplifier configuration), the input impedance of the amplifier is high, and the output impedance is low. The characteristics of the input and output impedance is beneficial for applications that require isolation between the input and output. No significant loading will occur from the previous stage before the amplifier. The gain of the system is set accordingly so the output signal is a factor larger than the input signal.

8.2 Typical Application

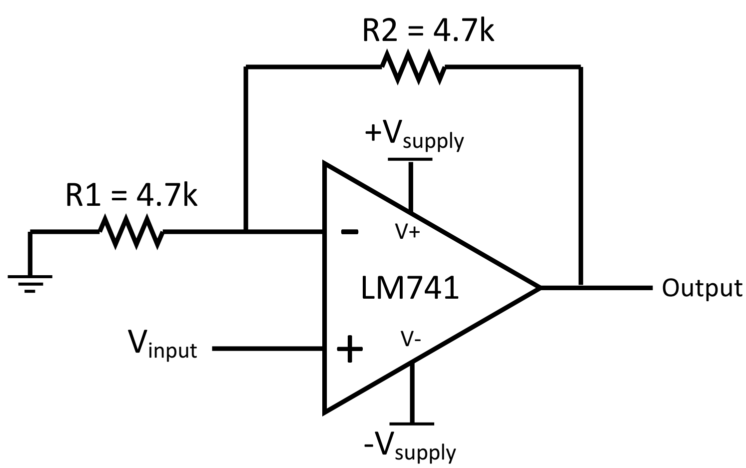


Figure 1. LM741 Noninverting Amplifier Circuit

8.2.1 Design Requirements

As shown in Figure 1, the signal is applied to the noninverting input of the LM741. The gain of the system is determined by the feedback resistor and input resistor connected to the inverting input. The gain can be calculated by Equation 1:

$$\text{Gain} = 1 + (R2/R1) \quad (1)$$

The gain is set to 2 for this application. R1 and R2 are 4.7-k resistors with 5% tolerance.

8.2.2 Detailed Design Procedure

The LM741 can be operated in either single supply or dual supply. This application is configured for dual supply with the supply rails at ±15 V. The input signal is connected to a function generator. A 1-Vpp, 10-kHz sine wave was used as the signal input. 5% tolerance resistors were used, but if the application requires an accurate gain response, use 1% tolerance resistors.

Typical Application (continued)

8.2.3 Application Curve

The waveforms in Figure 2 show the input and output signals of the LM741 non-inverting amplifier circuit. The blue waveform (top) shows the input signal, while the red waveform (bottom) shows the output signal. The input signal is 1.06 Vpp and the output signal is 1.94 Vpp. With the 4.7-kΩ resistors, the theoretical gain of the system is 2. Due to the 5% tolerance, the gain of the system including the tolerance is 1.992. The gain of the system when measured from the mean amplitude values on the oscilloscope was 1.83.

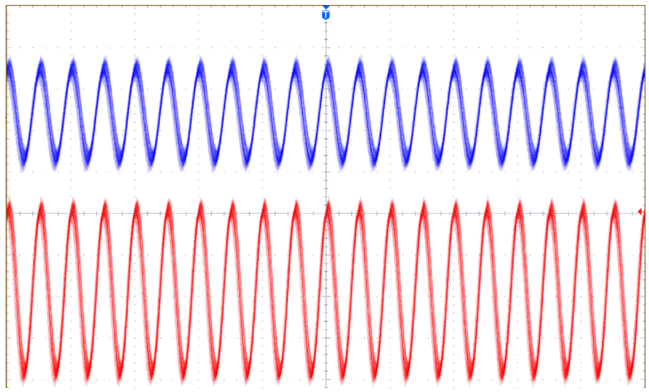


Figure 2. Waveforms for LM741 Noninverting Amplifier Circuit

9 Power Supply Recommendations

For proper operation, the power supplies must be properly decoupled. For decoupling the supply lines, a 0.1-µF capacitor is recommended and should be placed as close as possible to the LM741 power supply pins.

10 Layout

10.1 Layout Guidelines

As with most amplifiers, take care with lead dress, component placement, and supply decoupling in order to ensure stability. For example, resistors from the output to an input should be placed with the body close to the input to minimize pick-up and maximize the frequency of the feedback pole by minimizing the capacitance from the input to ground. As shown in Figure 3, the feedback resistors and the decoupling capacitors are located close to the device to ensure maximum stability and noise performance of the system.

10.2 Layout Example

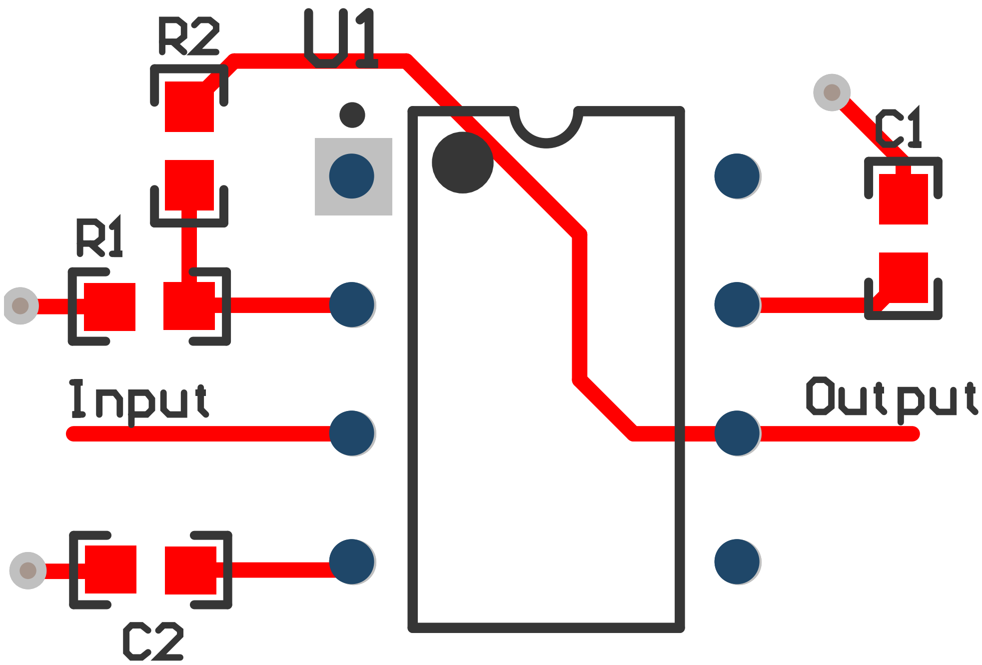


Figure 3. LM741 Layout

11 Device and Documentation Support

11.1 Community Resources

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's Terms of Use.

TI E2E™ Online Community ***TI's Engineer-to-Engineer (E2E) Community.*** Created to foster collaboration among engineers. At e2e.ti.com, you can ask questions, share knowledge, explore ideas and help solve problems with fellow engineers.

Design Support ***TI's Design Support*** Quickly find helpful E2E forums along with design support tools and contact information for technical support.

11.2 Trademarks

E2E is a trademark of Texas Instruments.
All other trademarks are the property of their respective owners.

11.3 Electrostatic Discharge Caution

These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

11.4 Glossary

SLYZ022 — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

12 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
LM741C-MWC	ACTIVE	WAFERSALE	YS	0	1	Green (RoHS & no Sb/Br)	Call TI	Level-1-NA-UNLIM	-40 to 85		Samples
LM741CN/NOPB	ACTIVE	PDIP	P	8	40	Green (RoHS & no Sb/Br)	CU SN	Level-1-NA-UNLIM	0 to 70	LM 741CN	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".
RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.
Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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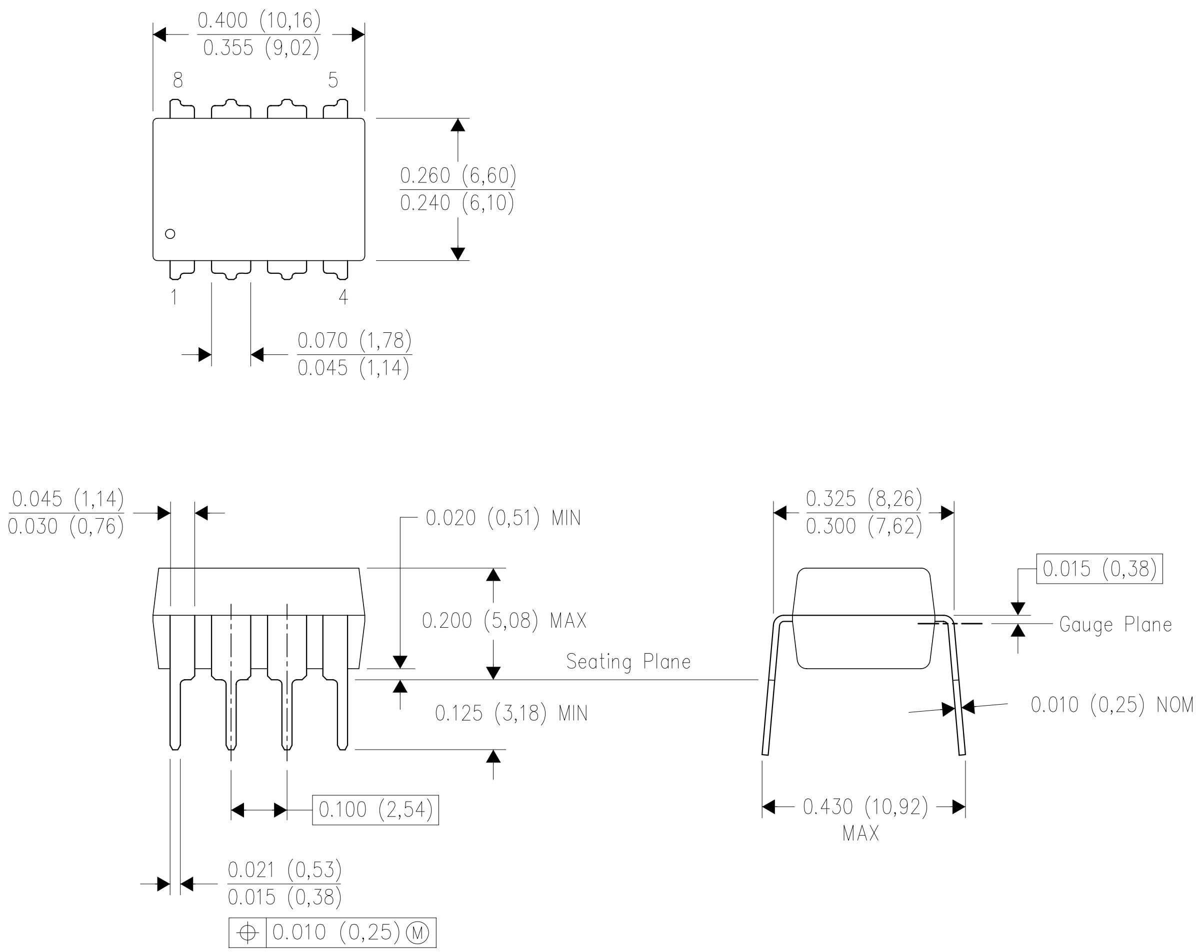
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

P (R–PDIP–T8) PLASTIC DUAL–IN–LINE PACKAGE



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NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001 variation BA.

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Tema n. 2

Una società è proprietaria di un gruppo di edifici di grandi dimensioni, utilizzati come uffici. Si vuole sviluppare un sistema automatico per il controllo della temperatura degli ambienti interni, bilanciando risparmio energetico e benessere.

Ciascun edificio ha quattro lati – orientati secondi i punti cardinali – e diversi piani.

Per ciascun lato dell'edificio e per ciascun piano, si ha in dotazione una coppia di dispositivi, ciascuno in grado di agire sia da sensore che da trasduttore:

- un sistema attivo di controllo dell'energia solare trasmessa all'interno dell'edificio dalle pareti vetrate;
- un ventilconvettore (fan coil).

Entrambi i dispositivi accettano comandi solo da alcuni pulsanti posti sui dispositivi stessi.

Il candidato elabori al meglio almeno sei dei seguenti punti.

1. Quali tecnologie hardware e software utilizzerebbe per rendere interconnessi con un calcolatore remoto l'insieme di coppie di dispositivi summenzionati.
2. Una volta resi i dispositivi in grado di ricevere comandi e trasmettere i dati fisici di competenza, si tracci un diagramma architetturale del sistema complessivo.
3. Si disegni un diagramma entità-relazione per l'organizzazione dei dati raccolti.
4. Un sequence diagram per almeno uno dei due tipi di dispositivi, relativamente alla comunicazione con il sistema centrale.
5. Un elenco - corredato dalle opportune giustificazioni - di quali linguaggi, sistemi operativi, protocolli e eventuali servizi terzi utilizzerebbe per il sistema centrale, distinguendo tra la parte di pure memorizzazione/elaborazione dei dati e quella di presentazione/interazione con l'utente.
6. Nella modellazione del sistema di controllo centralizzato, come utilizzerebbe - a integrazione delle informazioni raccolte dai sensori - la serie storica dei dati relativi all'irraggiamento solare di quella zona, per ciascun punto cardinale.
7. Nella modellazione del sistema di controllo centralizzato, come utilizzerebbe - a integrazione delle informazioni raccolte dai sensori - la possibilità di sfruttare un servizio di previsioni meteorologiche.
8. Nel caso si siano ormai raccolte sufficienti informazioni, indicare come si potrebbe sviluppare un sistema predittivo, specificando a quali famiglie di algoritmi di apprendimento si potrebbe fare riferimento.
9. Quali problemi di latenza potrebbero essere presenti nel sistema e quali contromisure si potrebbero mettere in campo, relativamente sia alle costanti di tempo fisiche trattate che alla natura distribuita dell'architettura.
10. Quali contromisure o persino architetture alternative potrebbero essere impiegate per aumentare la robustezza complessiva del sistema ai guasti o alla propagazione di informazioni false.
11. Quali metodologie di sviluppo e, in generale, di ingegneria del software si potrebbero applicare per ridurre i ricircoli e procedere in uno sviluppo il più parallelo possibile relativamente ai diversi sottoprogetti da interconnettere.
12. Quali aspetti essenziali di sicurezza dovrebbero essere presi in considerazione in fase di progetto.